

Serial No.: 09/997,019

REMARKS

No new matter has been added. The Applicants again request entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



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Date: February 12, 2002

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Enclosures: Version of Claims with Markings to Show Changes Made



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VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

2. (Amended) The method of claim 1, wherein said applying said second material comprises applying a[layer of] stress buffer material to said first material layer.

16. (Amended) The method of claim 11, wherein said [etching]planarizing is effected until said surface of said semiconductor device structure is exposed through said first material layer.

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